

Electronic Patent Application Fee Transmittal

Application Number:	10720579			
Filing Date:	24-Nov-2003			
Title of Invention:	Method for manufacturing very low roughness electrodeposited copper foil and electrodeposited copper foil manufactured thereby			
First Named Inventor/Applicant Name:	Sangyum Kim			
Filer:	Andrew W. Chu			
Attorney Docket Number:	1772-5			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Petition-revive unintent. abandoned appl	1453	1	1620	1620
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1620